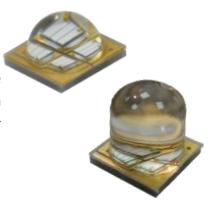


# N5050U-UNx2 Series High Power UV LED

## Introduction

The N5050U-UNx2 product series is a compact, high quality and reliable 4-chip UV LED. Featuring high radiometric power density and design flexibility — the N5050U-UNx2 spectrum can be tailored to your application.



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## **Characteristics**

## Absolute Maximum Ratings (T<sub>i</sub>=25°C)

Dayamakay	Rating N5050U-UNx2 Series			
Parameter				
DC Forward Current (mA)	350 mA			
Max Forward Current (mA)	700 mA			
LED Junction Temperature	150°C			
LED Operating Temperature	-40°C~85°C			
Storage Temperature	-40°C~125°C			
Soldering Temperature	Max. 260°C / Max. 10sec. (JEDEC 020)			
ESD Sensitivity	2,000 V HBM (JESD-22A-114-B)			
Reverse Voltage	Not designed to be driven in reverse bias (VR≦5V)			
Preconditioning	Acc. to JEDEC Level 1			

- 1. The peak wavelength is measured with an accuracy of ±1nm
- 2. All values stated are subject to the limits and set up of TSLC's testers. All other measurement data are defined as long-term production mean values and are only given for reference.
- 3. A critical component is a component used in a life-support device or system whose failure can reasonably be expected to cause the failure of that life-support device or system, or to affect its safety or effectiveness of that device or system. Life support devices or systems are intended (i) to be implanted in the human body, or (ii) to support and/or maintain and sustain human life. If they fail, it is reasonable to assume that the health of the user may be endangered. Components used as a critical component must be approved in writing by TSLC Corporation.
- 4. These devices emit high intensity UV/NUV light. Necessary precautions must be taken during operation. Do not look directly into the light or look through the optical system when in operation. Protective eyewear should be worn at all times during operation.
- 5. Do not drive at rated current for more than 5 seconds without proper thermal management.
- 6. Always follow thermal design recommendations in the relevant Application Note.
- 7. Lens discoloration may occur with prolonged exposure to UN/NUV light. Additional lens material will need to be tested for UN/NUV light compatibility and durability.

## **General Characteristics at 350mA**

Part number	Color	Peak Wavelength λp		2θ <sub>1/2</sub>	Thermal Resistance Junction to Pad (°C/W)
		Min	Max		R⊝ <sub>J-L</sub>
	U40	380	390	135	1.5
N5050U-UNL2	U50	390	400	135	1.5
	U60	400	410	135	1.5
	U70	410	420	135	1.5
	U40	380	390	65	1.5
N5050U-UNF2	U50	390	400	65	1.5
	U60	400	410	65	1.5
	U70	410	420	65	1.5

Notes: The peak wavelength is measured with an accuracy of ±1nm

# Radiometric Power and Forward Voltage (T<sub>j</sub>=25°C)

		Performance at Test Current (350mA)					Performance at 700mA
Part number	Color	Group	Radiometric Power (mW)		VF		Calculated Minimum  Radiometric Power*
			Min	Max	Min	Max	(mW)
		NHS	1600	1800	11	15	2900
	U40	NI1	1800	2000	11	15	3200
	(380-390nm)	NI2	2000	2200	11	15	3600
		NI3	2200	2400	11	15	3900
		NHS	1600	1800	11	15	2900
	U50 (390-400nm)	NI1	1800	2000	11	15	3200
		NI2	2000	2200	11	15	3600
		NI3	2200	2400	11	15	3900
N.50501111112		NI4	2400	2600	11	15	4300
N5050U-UNL2 (beam angle 135°)		NHS	1600	1800	11	15	2900
(beam angle 133 )	1160	NI1	1800	2000	11	15	3200
	U60 (400-410nm)	NI2	2000	2200	11	15	3600
		NI3	2200	2400	11	15	3900
		NI4	2400	2600	11	15	4300
	U70 (410-420nm)	NHS	1600	1800	11	15	2900
		NI1	1800	2000	11	15	3200
		NI2	2000	2200	11	15	3600
		NI3	2200	2400	11	15	3900
		NI4	2400	2600	11	15	4300

Note: 1. Radiometric power is measured with an accuracy of ±10%

<sup>2.</sup> The forward voltage is measured with an accuracy of  $\pm 0.2V$ 

<sup>\*</sup> Calculated values are for reference only.

		Performance at Test Current (350mA)					Performance at 700mA
Part number	Color	Group	Radiometric Power (mW)		VF		Calculated Minimum  Radiometric Power*
			Min	Max	Min	Max	(mW)
		NHR	1400	1600	11	15	2500
	1140	NHS	1600	1800	11	15	2900
	U40 (380-390nm)	NI1	1800	2000	11	15	3200
	(300 3301111)	NI2	2000	2200	11	15	3600
		NI3	2200	2400	11	15	3900
		NHR	1400	1600	11	15	2500
		NHS	1600	1800	11	15	2900
	U50 (390-400nm)	NI1	1800	2000	11	15	3200
		NI2	2000	2200	11	15	3600
		NI3	2200	2400	11	15	3900
NIE 0 E 0 I I I I I I I		NI4	2400	2600	11	15	4300
N5050U-UNF2 (beam angle 65°)		NHR	1400	1600	11	15	2500
(beam angle 05 )		NHS	1600	1800	11	15	2900
	U60 (400-410nm)	NI1	1800	2000	11	15	3200
		NI2	2000	2200	11	15	3600
		NI3	2200	2400	11	15	3900
		NI4	2400	2600	11	15	4300
		NHR	1400	1600	11	15	2500
	U70 (410-420nm)	NHS	1600	1800	11	15	2900
		NI1	1800	2000	11	15	3200
		NI2	2000	2200	11	15	3600
		NI3	2200	2400	11	15	3900
		NI4	2400	2600	11	15	4300

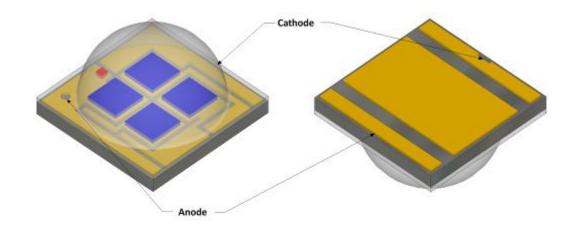
Note: 1. Radiometric power is measured with an accuracy of ±10%

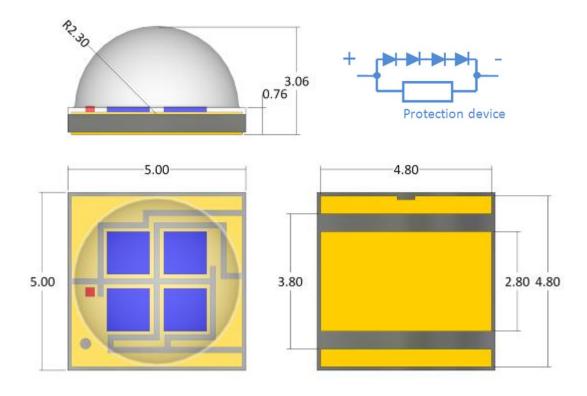
<sup>2.</sup> The forward voltage is measured with an accuracy of  $\pm 0.2V$ 

<sup>\*</sup> Calculated values are for reference only.

# **Mechanical Dimensions**

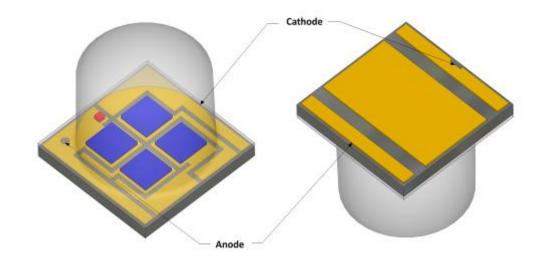
## N5050U-UNL2 (beam angle 135°)

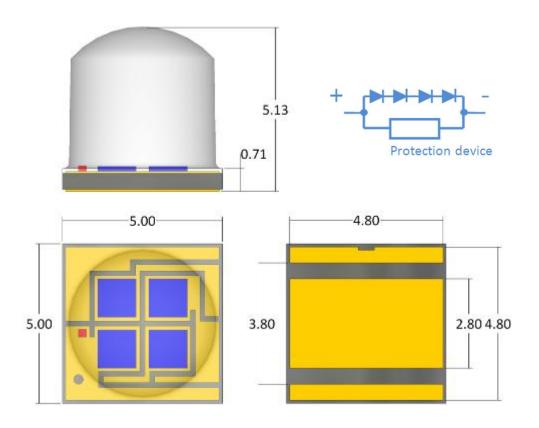




- 1. Drawing is not to scale
- 2. All dimensions are in millimeter
- 3. Dimensions are  $\pm 0.13$ mm unless otherwise indicated

## N5050U-UNF2 (beam angle 65°)

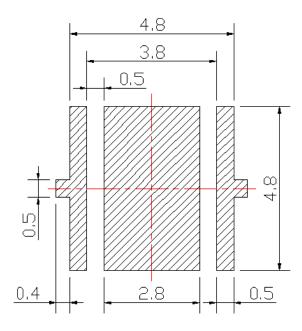




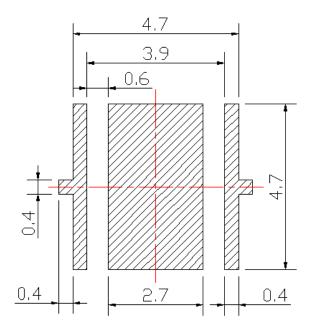
- 1. Drawing is not to scale
- 2. All dimensions are in millimeter
- 3. Dimensions are  $\pm 0.13$ mm unless otherwise indicated

# **Recommended Solder Pad Design**

## **Recommended Soldering Pad Design**

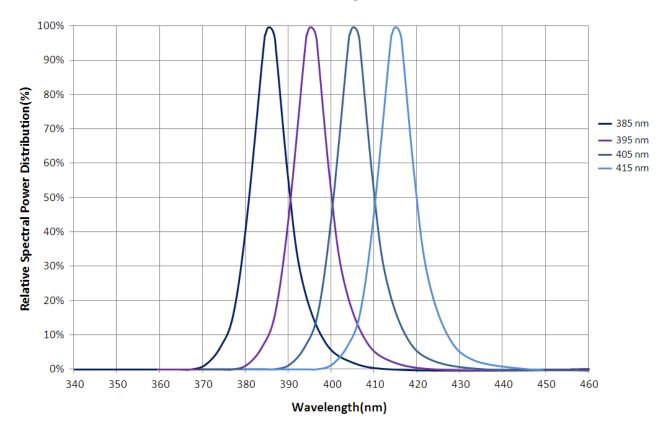


# **Recommended Stencil Pattern Design (Marked Area is Opening)**



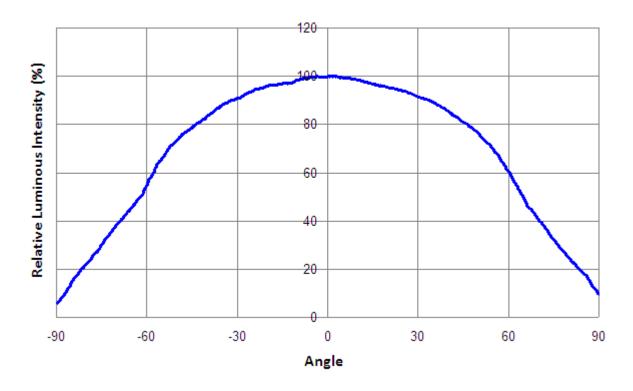
- 1. Drawing is not to scale
- 2. All dimensions are in millimeter

# Relative Spectral Power Distribution, T<sub>j</sub>=25°C

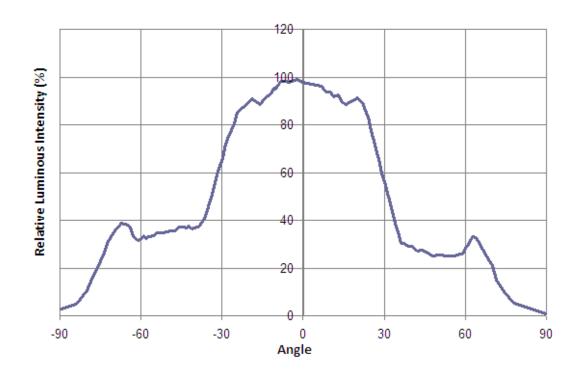


# **Typical Spatial Radiation Pattern**

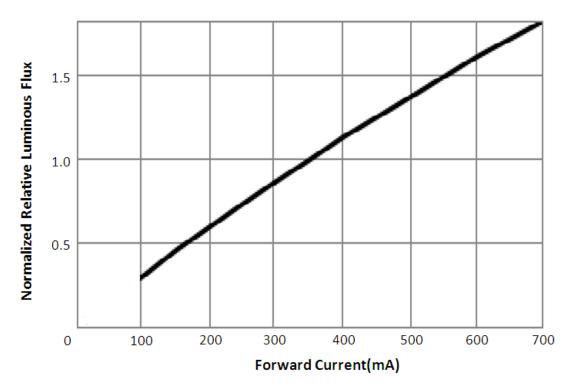
# N5050U-UNL2 (beam angle 135°)



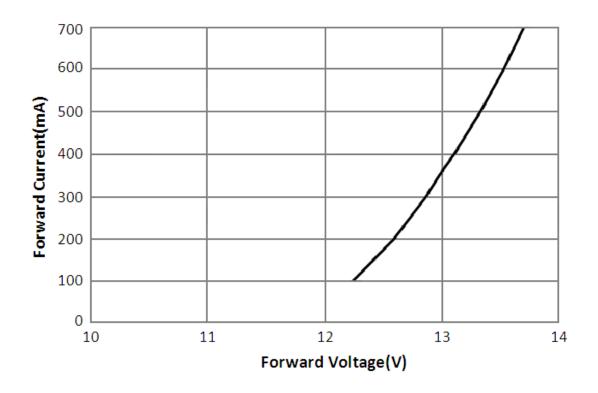
# N5050U-UNF2 (beam angle 65°)



# Typical Forward L-I Characteristics, T<sub>j</sub>=25°C

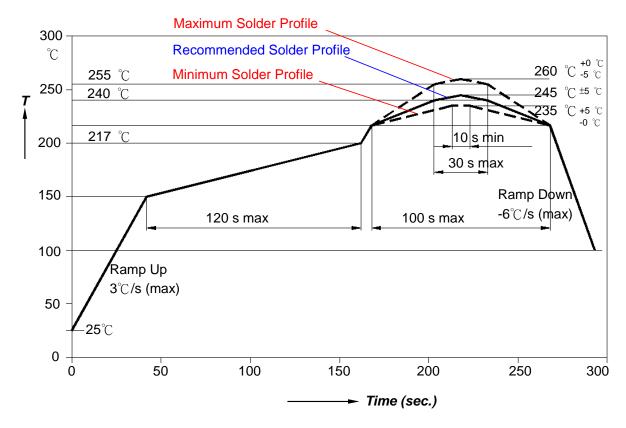


# **Typical Forward I-V Characteristics, T<sub>j</sub>=25°C**



# **Recommended Soldering Profile**

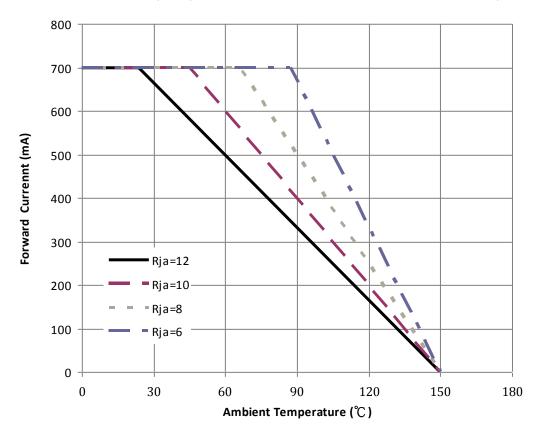
The LEDs can be soldered using the parameters listed below. As a general guideline, the users are suggested to follow the recommended soldering profile provided by the manufacturer of the solder paste. Although the recommended soldering conditions are specified in the list, reflow soldering at the lowest possible temperature is advised for the LEDs.



Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average Ramp-up Rate (Ts <sub>max</sub> to Tp)	3°C/second max.	3°C/second max.
Preheat - Temperature Min(Ts <sub>min</sub> ) - Temperature Max(Ts <sub>max</sub> ) - Time(ts <sub>min</sub> to ts <sub>max</sub> )	100°C 150°C 60-120 seconds	150°C 200°C 60-180 seconds
Time maintained above: - Temperature(T <sub>L</sub> ) - Time(t <sub>L</sub> )	183°C 60-150 seconds	217°C 60-150 seconds
Peak/classification Temperature(Tp)	215°C	260°C
Time within 5°C of actual Peak Temperature(tp)	10-30 seconds	20-40 seconds
Ramp-Down Rate	6°C/second max.	6°C/second max.
Time 25℃ to Peak Temperature	6 minutes max.	8 minutes max.

# **Thermal Design**

Thermal design of the end product is important. The thermal resistance between the junction and the solder point  $(R\Theta_{J-P})$  and the end product should be designed to minimize the thermal resistance from the solder point to ambient in order to optimize the emitter life and optical characteristics. The maximum operation current is determined by the plot of Allowable Forward Current vs. Ambient Temperature.



The junction temperature can be correlated to the thermal resistance between the junction and ambient (Rja) by the following equation.

Tj: LED junction temperature

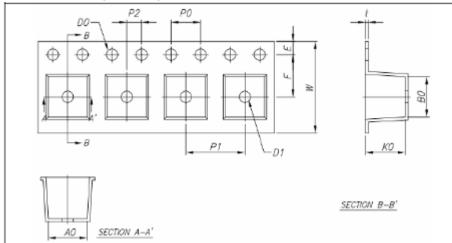
Ta: Ambient temperature

Rja: Thermal resistance between the junction and ambient

W: Input power ( $I_F*V_F$ )

# **Packing Information**

# Dimensions. (Unit: mm)



## Common dimensions

Item	Specification	Tol. (+/-)
W	12.00	±0.20
Е	1.75	±0.10
F	5.50	±0.10
D0	1.50	±0.10
D1	1.50	±0.10
P0	4.00	±0.10
P1	8.00	±0.10
P2	2.00	±0.10
P0x10	40.00	±0.20

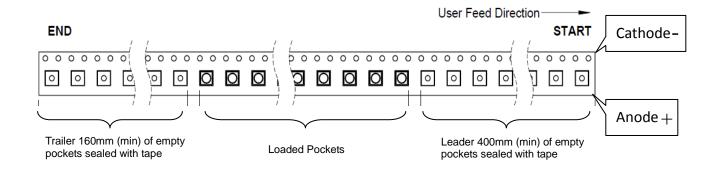
#### Pocket & other dimensions

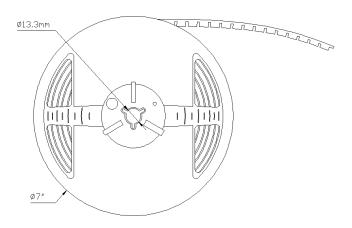
#### N5050U-UNL2 series

Item	Specification	Tol. (+/-)
t	0.28	±0.05
A0	5.35	±0.10
B0	5.35	±0.10
K0	3.40	±0.10

#### N5050U-UNF2 series

Item	Specification	Tol. (+/-)
t	0.40	±0.05
A0	5.30	±0.10
B0	5.30	±0.10
K0	5.40	±0.10





## **About Us**

**TSLC Corporation** is devoted to developing high-density, and multi-size emitters with powerful output to satisfy the needs of every customer.

**TSLC Corporation** is the leader in LED solutions. Unlimited design flexibility for interior and exterior spaces with high-end lighting effect; energy-efficient for UV curing to improve the quality of medical care; horticulture solutions create a better environment for everyone; high-intensity rotatable lightings for the entertainment industry, TSLC is always there for your lighting needs.

For further company or product information, please visit us at www.tslc.com.tw or please contact sales@ tslc.com.tw.





www.tslc.com.tw

## **ASIA PACIFIC**

1F, No. 11, Ke Jung Rd. Chu-Nan Site Hsinchu Science Park Chu-Nan 350, Miao-Li City Taiwan, ROC

> Tel: +886-37-587098 Fax: +886-37-587099 sales@tslc.com.tw